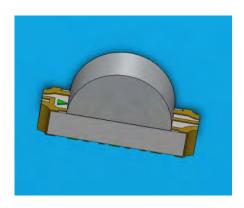


DATASHEET

SMD LED EASV3015RGYA3



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Multi-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

The EASV3015RGYA3 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained. Besides, lightweight makes them ideal for miniture applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.



Device Selection Guide

Chip			D 1 G1	
Type	Material	Emitted Color	Resin Color	
R6	AlGaInP	Brilliant Red		
Y2	AlGaInP	Brilliant Yellow	Water Clear	
G6	AlGaInP	Brilliant Yellow Green		

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	Ifp	R6:60 Y2:60 G6:60	mA
Power Dissipation	Pd	R6:60 Y2:60 G6:60	mW
Electrostatic Discharge (HBM)	ESD	R6:2000 Y2:2000 G6:2000	V
Operating Temperature	Topr	- 40 ∼ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tstg	- 40 ∼ +90	$^{\circ}\!$
Soldering Temperature Tsol		Reflow Soldering : 260 Hand Soldering : 350	



Electro-Optical Characteristics (Ta=25°C)

Parameter	Syn	nbol	Min.	Тур.	Max.	Unit	Condition
		R6	45.0		112.0		
Luminous Intensity	Iv	Y2	45.0		112.0	mcd	
		G6	45.0		112.0		
Viewing Angle	2θ	1/2		100		deg	
		R6		632			
Peak Wavelength	λр	Y2		591		nm	
		G6		575			
		R6	617.5		633.5		
Dominant Wavelength	λd	Y2	585.5		594.5	nm	I _F =20mA
		G6	569.5		575.5		
		R6		20			
Spectrum Radiation Bandwidth	Δλ	Y2		15		nm	
		G6		20			
		R6	1.7	2.0	2.4		
Forward Voltage	VF	Y2	1.7	2.0	2.4	V	
		G6	1.7	2.0	2.4		
		R6			10		
Reverse Current	Ir	Y2			10	μ A	$V_R=5V$
		G6			10		

Notes:

1.Tolerance of Luminous Intensity ±11%

2.Tolerance of Dominant Wavelength ±1nm



Bin Range Of Luminous Intensity

R6

Bin	Min	Max	Unit	Condition
P	45.0	72.0	1	I 20 A
Q	72.0	112	mcd	I _F =20mA

Y2

Bin	Min	Max	Unit	Condition
P	45.0	72.0	1	I 20 A
Q	72.0	112	mcd	I _F =20mA

G6

Bin	Min	Max	Unit	Condition
P	45.0	72.0		. 20 A
Q	72.0	112	mcd	$I_F=20\text{mA}$

Notes:

Tolerance of Luminous Intensity $\pm 11\%$



Bin Range Of Dom. Wavelength

R6

Groups	Bin	Min	Max	Unit	Condition	
A	E4	617.5	621.5			
	E5	621.5	625.5	nm	I _F =20mA	
	Е6	625.5	629.5			
	E7	629.5	633.5			

Y2

Groups	Bin	Min	Max	Unit	Condition
	D3	585.5	588.5		
A	D4	588.5	591.5	nm	$I_F=20mA$
	D5	591.5	594.5		
G6					

G6

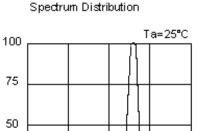
Groups	Bin	Min	Max	Unit	Condition
М	C16	569.5	571.5	nm	I _F =20mA
	C17	571.5	573.5		
	C18	573.5	575.5		

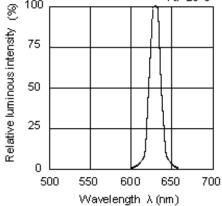
Notes:

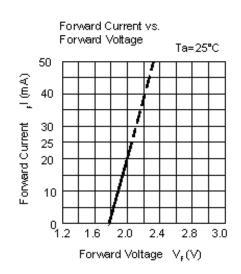
Tolerance of Dominant Wavelength ±1nm

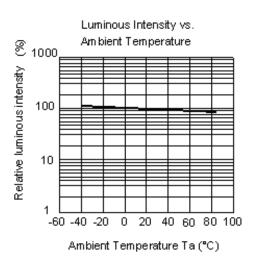


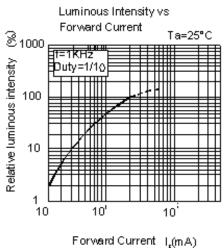
Typical Electro-Optical Characteristics Curves R6

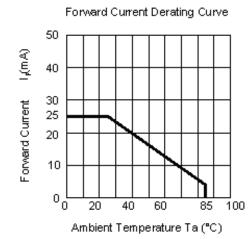


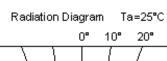


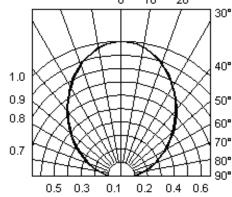






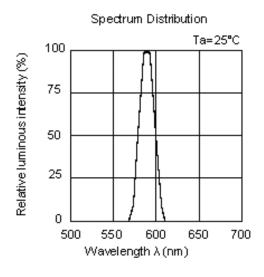


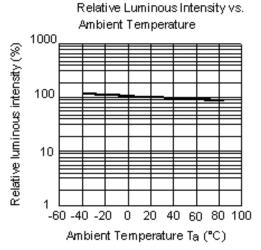


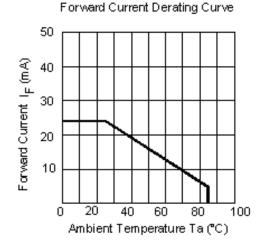


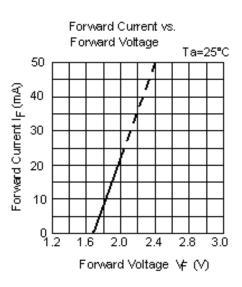


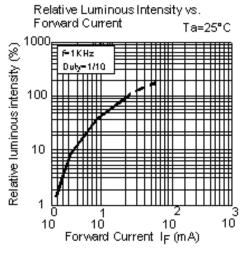
Typical Electro-Optical Characteristics Curves Y2

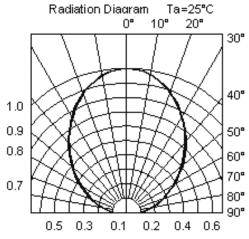






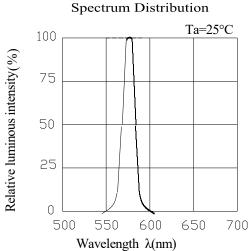


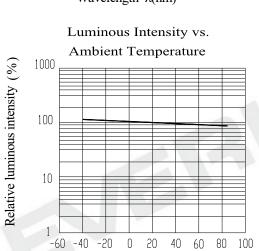




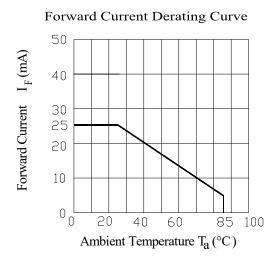


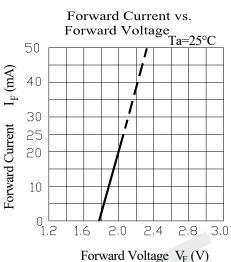
$\begin{array}{c} \textbf{Typical Electro-Optical Characteristics Curves} \\ \textbf{G6} \end{array}$

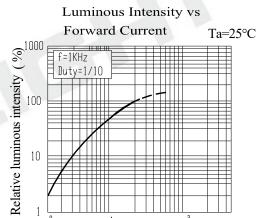




Ambient Temperature $T_a(^{\circ}C)$



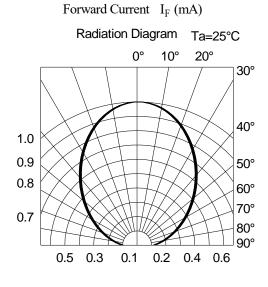




10¹

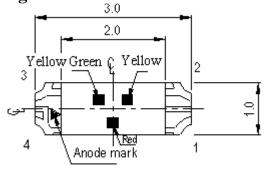
10

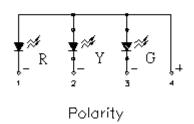
. 10°

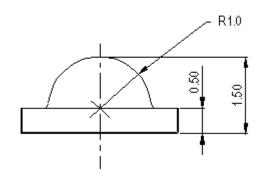




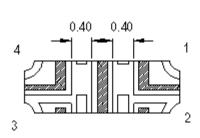
Package Outline Dimensions

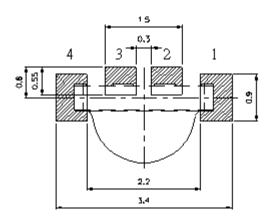






For reflow soldering (propose)





Note: The tolerances unless mentioned is ± 0.1 mm,Unit = mm

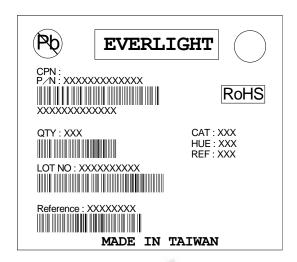


Label explanation

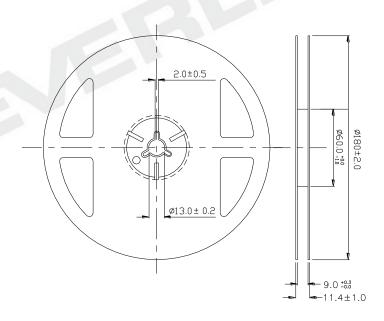
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank



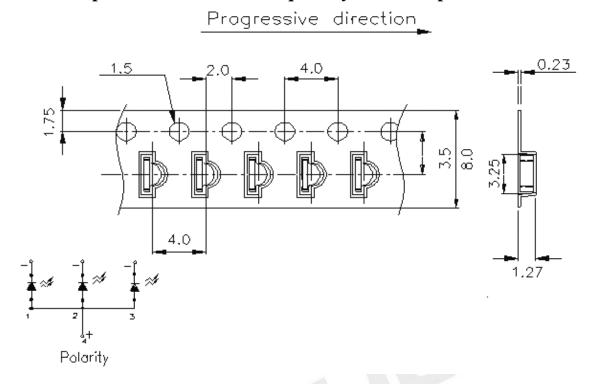
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

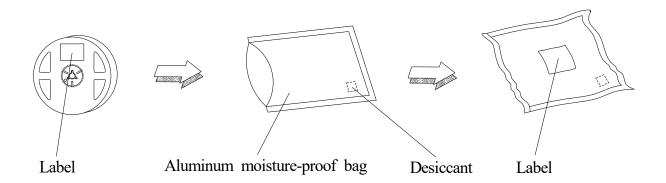


Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Moisture Resistant Packaging





Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	$H: +100^{\circ}\mathbb{C}$ 15min \int 5 min $L: -40^{\circ}\mathbb{C}$ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H:+100°C 5min ∫ 10 sec L:-10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

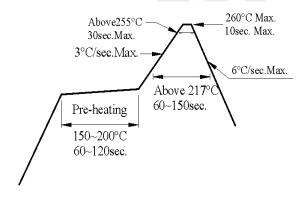
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.



4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

